



Features

- ★ Advanced Trench MOS Technology
- ★ 100% EAS Guaranteed
- ★ Super Low RDS_(ON)
- ★ Green Device Available

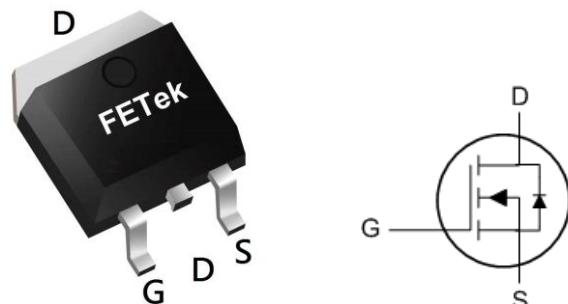
Product Summary

BVDSS	RDS _{ON}	ID
100V	4.5mΩ	120A

Applications

- ★ MOTOR Driver.
- ★ BMS.
- ★ High frequency switching and synchronous rectification.

TO263 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	100	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ^{1,6}	120	A
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ^{1,6}	100	A
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	15.6	A
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	12.4	A
I _{DM}	Pulsed Drain Current ²	480	A
EAS	Single Pulse Avalanche Energy ³	702	mJ
I _{AS}	Avalanche Current	53	A
P _D @T _C =25°C	Total Power Dissipation ⁴	250	W
P _D @T _C =100°C	Total Power Dissipation ⁴	100	W
P _D @T _A =25°C	Total Power Dissipation ⁴	2.0	W
P _D @T _A =70°C	Total Power Dissipation ⁴	1.3	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	62	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	0.5	°C/W



FETek Technology Corp.

FKH15810C

N-Ch 100V Fast Switching MOSFETs

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

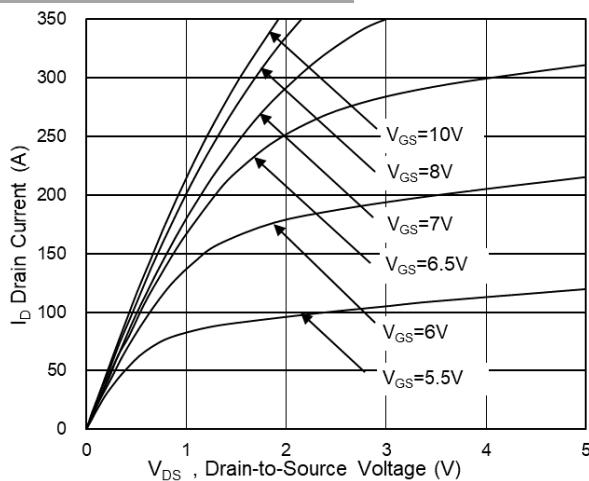
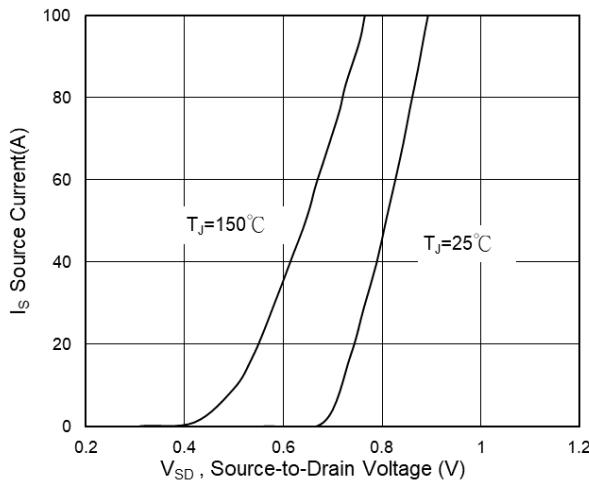
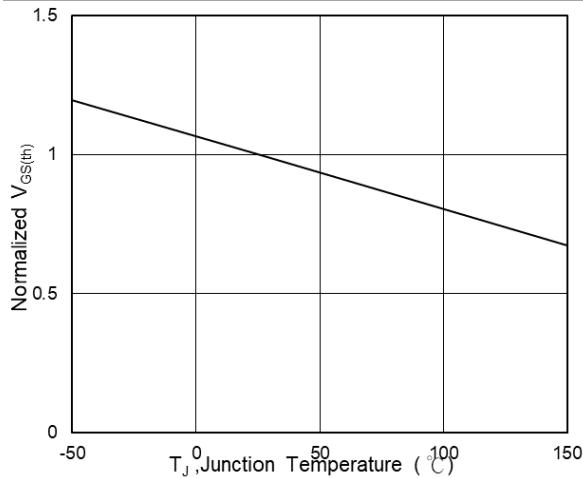
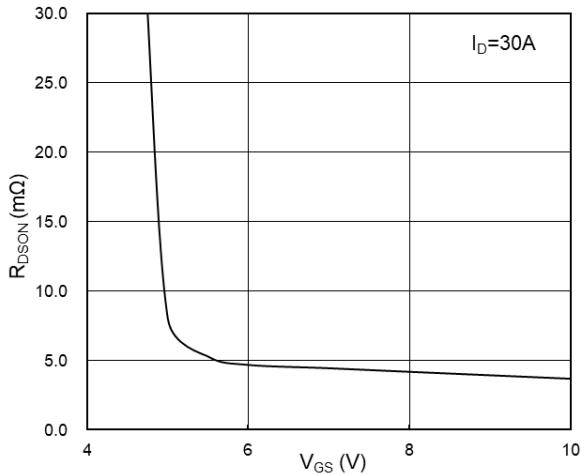
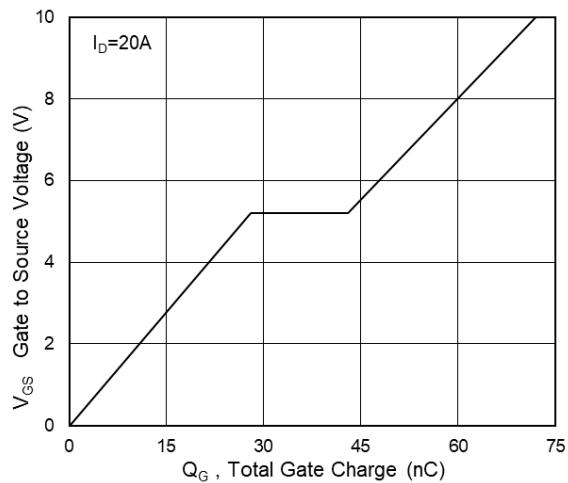
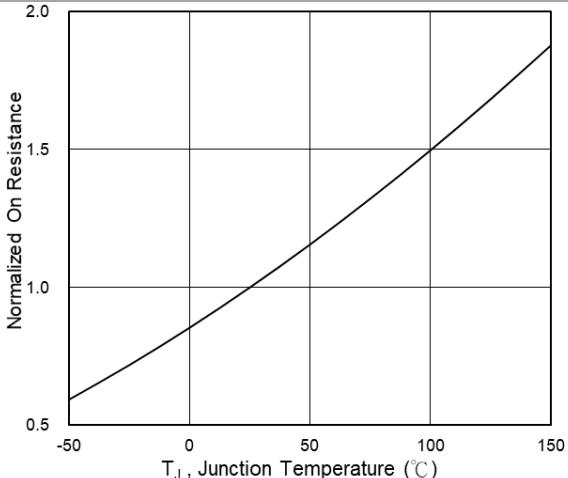
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	100	---	---	V
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=10\text{V}$, $I_D=30\text{A}$	---	3.7	4.5	$\text{m}\Omega$
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	2.5	3.0	4.0	V
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=100\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{\text{DS}}=100\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	10	
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{\text{DS}}=5\text{V}$, $I_D=30\text{A}$	---	50	---	S
R_g	Gate Resistance	$V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	1	---	Ω
Q_g	Total Gate Charge (10V)	$V_{\text{DS}}=50\text{V}$, $V_{\text{GS}}=10\text{V}$, $I_D=20\text{A}$	---	72	---	nC
Q_{gs}	Gate-Source Charge		---	28	---	
Q_{gd}	Gate-Drain Charge		---	15	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=50\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_g=3.0\Omega$, $I_D=20\text{A}$	---	35	---	ns
T_r	Rise Time		---	18	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	45	---	
T_f	Fall Time		---	55	---	
C_{iss}	Input Capacitance	$V_{\text{DS}}=50\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	4725	---	pF
C_{oss}	Output Capacitance		---	609	---	
C_{rss}	Reverse Transfer Capacitance		---	14	---	

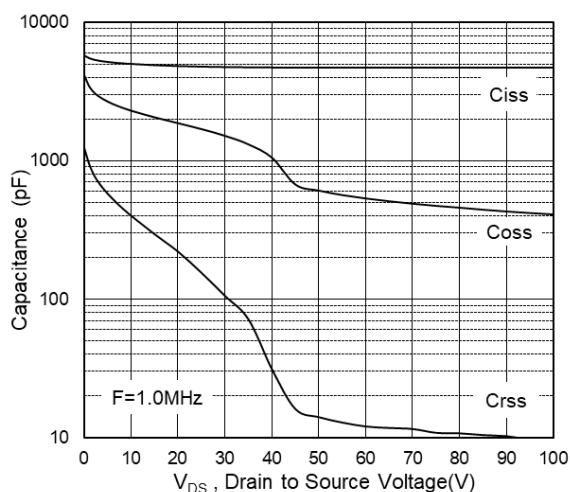
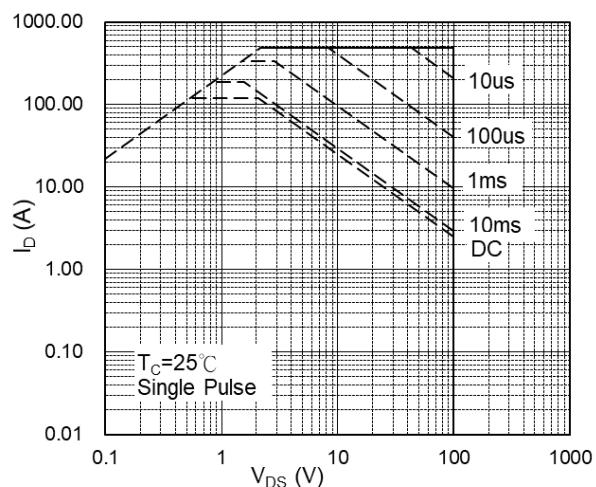
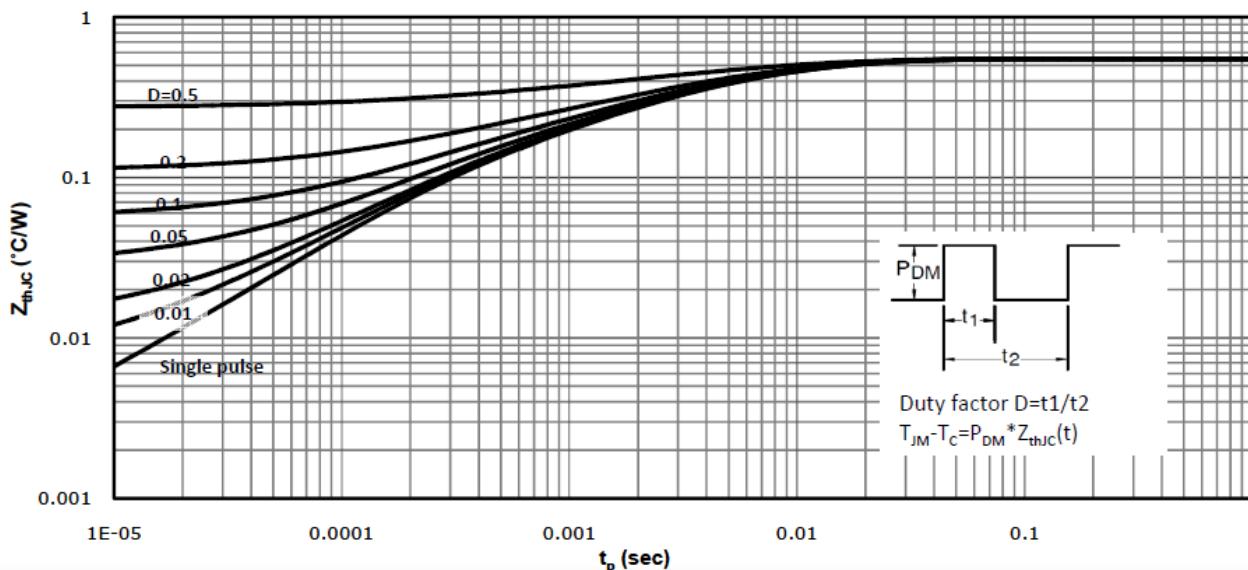
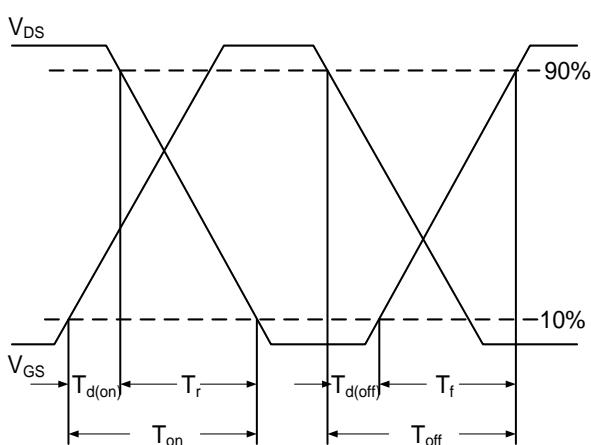
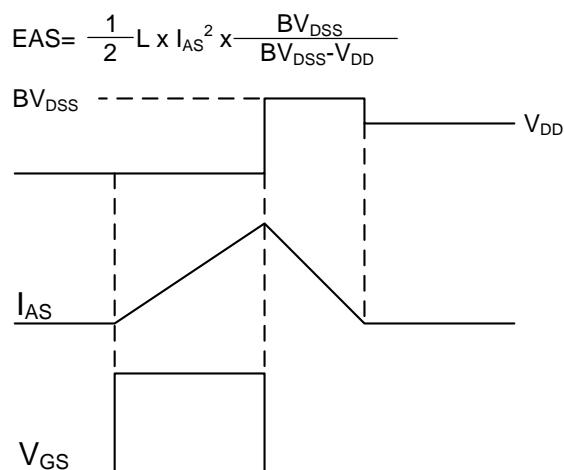
Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,5,6}	$V_G=V_D=0\text{V}$, Force Current	---	---	120	A
V_{SD}	Diode Forward Voltage ²	$V_{\text{GS}}=0\text{V}$, $I_s=50\text{A}$, $T_J=25^\circ\text{C}$	---	---	1.3	V
t_{rr}	Reverse Recovery Time	$ I_F =30\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$, $T_J=25^\circ\text{C}$	---	70	---	nS
Q_{rr}	Reverse Recovery Charge		---	170	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.5\text{mH}$, $I_{\text{AS}}=53\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.
- 6.Package limitation current.

Typical Characteristics

Fig.1 Typical Output Characteristics

Fig.3 Source Drain Forward Characteristics

Fig.5 Normalized V_{TH} vs T_J

Fig.2 On-Resistance vs G-S Voltage

Fig.4 Gate-Charge Characteristics

Fig.6 Normalized $R_{DS(on)}$ vs T_J


Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Switching Waveform